



## Material Content Data Sheet



<b>Sales Product Name</b>		TLD2141-3EP		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA002391824						
<b>Package</b>		PG-TSDSO-14-13		<b>Weight*</b>		64.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.174	3.39	3.39	33891	33891
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.037	0.06		582	
	non noble metal	iron	7439-89-6	0.746	1.16		11635	
wire	non noble metal	copper	7440-50-8	30.306	47.26	48.49	472418	484780
	non noble metal	copper	7440-50-8	0.086	0.13	0.13	1345	1345
	encapsulation	organic material	carbon black	1333-86-4	0.085	0.13		1326
plastics		epoxy resin	-	3.317	5.17		51711	
	inorganic material	silicondioxide	60676-86-0	24.950	38.89	44.19	388935	441972
leadfinish	non noble metal	tin	7440-31-5	1.644	2.56	2.56	25629	25629
plating	noble metal	silver	7440-22-4	0.135	0.21	0.21	2103	2103
glue	plastics	epoxy resin	-	0.165	0.26		2570	
	noble metal	silver	7440-22-4	0.495	0.77	1.03	7710	10280
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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